

**In the Specification:**

Please replace the title with the following rewritten title.

-- Thermal Dissipating Element of Chip--

Please replace the paragraph beginning at page 13, line 2, with the following rewritten paragraph.

--As shown in FIG. 5, the thermal dissipating element of the third embodiment of the present invention includes a plurality of holes between the side plate 25 and the sole plate 27. The packing material 291 is filling filled into the space between the cover 21 and the substrate 25 is ~~compressed into the cover 21~~. The bottom face 313 of the lump 31 is fastened on and contacts with the chip 33. The area of the bottom face 313 of the lump 31 equals to the area of the chip 33 to conduct the heat produced by the chip 33 more effectively. The area of the top face 311 of the lump 31 also equals to the area of the bottom surface 233 of the cover 21. Furthermore, a portion of the side 315, i.e. a part side 317, contacts with the side plate 25 to increase the conducted area between the lump 31 and the cover 21 for dissipating the heat more quickly and more uniform.--